TO: Examiner Mohammad Ali, art unit 3744

RE: Proposed claim amendments to 10/028,860

FROM: Glen Choi, Reg. No. 43,546

Enclosed are proposed claim amendments.

1. (Amended) An integrated circuit package comprising:

an integrated circuit die having an active surface; and

a cooling fluid to move laterally across and in contact with the active surface.

8. (Three Times Amended) A method of forming an integrated circuit package comprising:

attaching an interposer to a package substrate;

attaching an integrated circuit die to the interposer, wherein the integrated circuit die includes an active region;

covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;

filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die and wherein the cooling fluid contacts and is to move laterally across the active region.

12. (Amended) A method of cooling an integrated circuit die within an integrated circuit package comprising:

providing power to the integrated circuit die; and

moving a cooling fluid laterally across and in contact with an active surface of the integrated circuit die.

17. (Twice Amended) An integrated circuit package comprising:

a package substrate;

a first integrated circuit die having an active surface;

an interposer disposed between the package substrate and the first integrated circuit die, the interposer establishing electrical connectivity between the first integrated circuit die and the package substrate; and

a cooling fluid disposed between the first integrated circuit die and the interposer, wherein the cooling fluid is to move laterally across and in contact with ~~contacts~~ the active surface.

27. (Twice Amended) An integrated circuit package comprising:

a integrated circuit die housed within a chamber, wherein the integrated circuit die includes an active region; and

a cooling fluid filling the chamber and in contact with and to move laterally across the active region of the integrated circuit die.